

Title (en)

TEMPLATE FOR ELECTRONIC COMPONENT CLAMPING DEVICE AND CHECKING METHOD USING SAME

Title (de)

SCHABLONE FÜR VORRICHTUNG ZUM AUFSPANNEN ELEKTRONISCHER KOMPONENTEN UND PRÜFVERFAHREN DAMIT

Title (fr)

GABARIT DESTINÉ À UN DISPOSITIF DE SERRAGE DE COMPOSANT ÉLECTRONIQUE ET PROCÉDÉ DE VÉRIFICATION L'UTILISANT

Publication

**EP 3515164 A4 20190904 (EN)**

Application

**EP 16916234 A 20160915**

Priority

JP 2016077229 W 20160915

Abstract (en)

[origin: EP3515164A1] Template 10 is a plate-like template used for confirming whether a pair of claws 54 will interfere with another component 81 around mounting position 200 when the pair of claws 54 clamp electronic component 80 and mounts an electronic component on board 100. In electronic component clamping device 50, distance W54 between the pair of claws 54, when the pair of claws 54 is in the opened position, can be selected from multiple distances in accordance with the size of electronic component 80. Template 10 includes first region 12 having width W12 corresponding to a selected distance between the pair of claws 54 when the pair of claws 54 is in the opened position.

IPC 8 full level

**H05K 13/04** (2006.01); **G01D 5/26** (2006.01); **H05K 13/08** (2006.01)

CPC (source: EP US)

**G01D 5/26** (2013.01 - US); **H05K 13/0408** (2013.01 - EP US); **H05K 13/0812** (2018.07 - EP US); **H05K 13/085** (2018.07 - EP US)

Citation (search report)

- [A] WO 2016017029 A1 20160204 - FUJI MACHINE MFG [JP] & EP 3177128 A1 20170607 - FUJI MACHINE MFG [JP]
- [A] EP 3057391 A1 20160817 - FUJI MACHINE MFG [JP]
- [A] EP 0128899 A1 19841227 - WESTERN ELECTRIC CO [US]
- [A] US 4451324 A 19840529 - ICHIKAWA IWA O [JP], et al
- See references of WO 2018051451A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

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DOCDB simple family (application)

**EP 16916234 A 20160915**; CN 201680089274 A 20160915; JP 2016077229 W 20160915; JP 2018539020 A 20160915; US 201616330515 A 20160915